



# SOT1709-1

SO8, plastic, small outline package; 8 terminals; 1.27 mm pitch; 7.36 mm x 7.36 mm x 4.19 mm body

17 September 2018

Package information

## 1 Package summary

Terminal position code	D (double)
Package type descriptive code	SO8
Package type industry code	SO8
Package style descriptive code	SO (small outline)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	01-02-2016
Manufacturer package code	98ARH99066A

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7.36	-	mm
package width	-	7.36	-	mm
package height	-	4.19	-	mm
nominal pitch	-	1.27	-	mm
actual quantity of termination	-	8	-	



SO8, plastic, small outline package; 8 terminals; 1.27 mm pitch; 7.36 mm x 7.36 mm x 4.19 mm body

2 Package outline

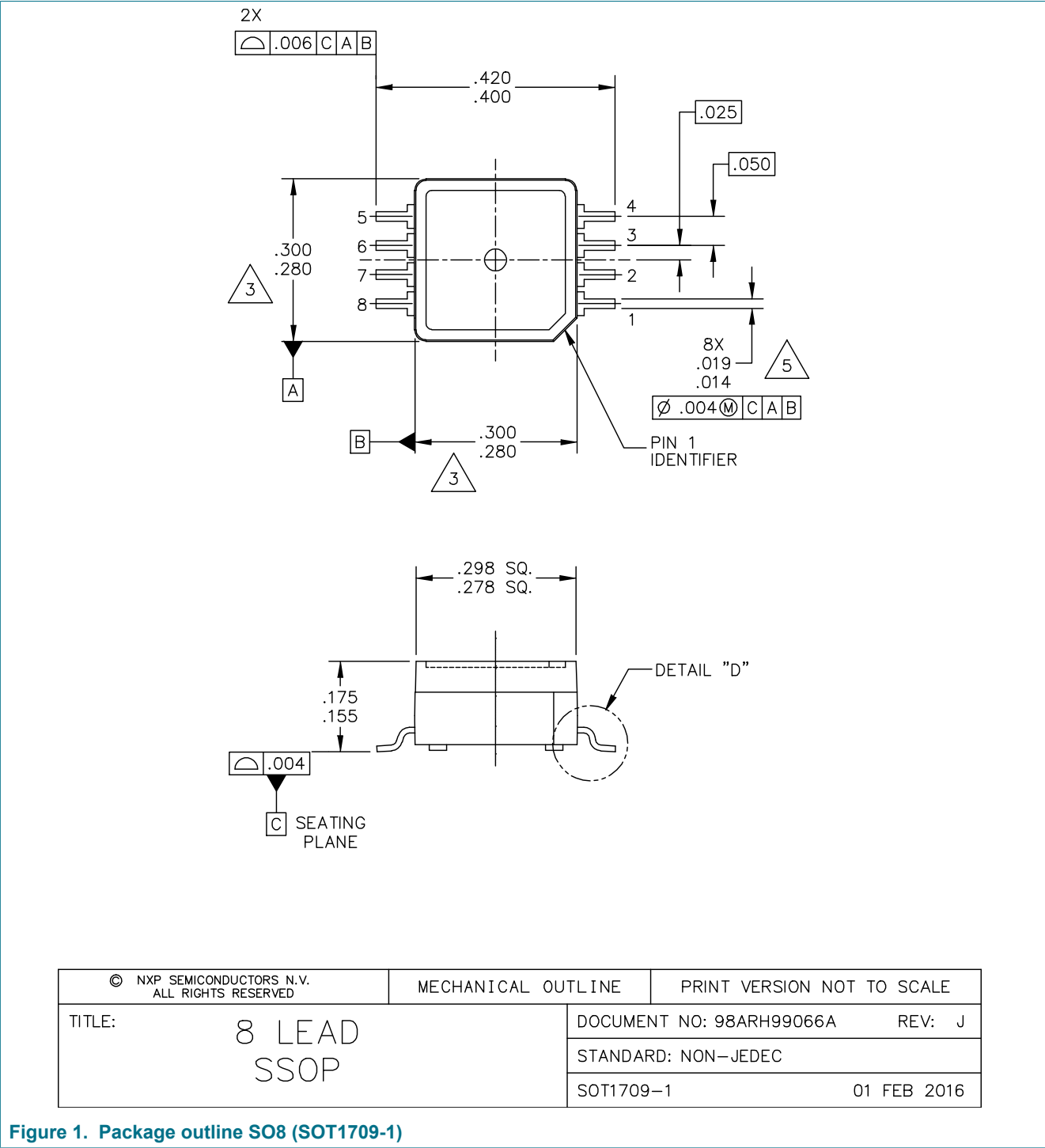


Figure 1. Package outline SO8 (SOT1709-1)

SO8, plastic, small outline package; 8 terminals; 1.27 mm pitch; 7.36 mm x 7.36 mm x 4.19 mm body

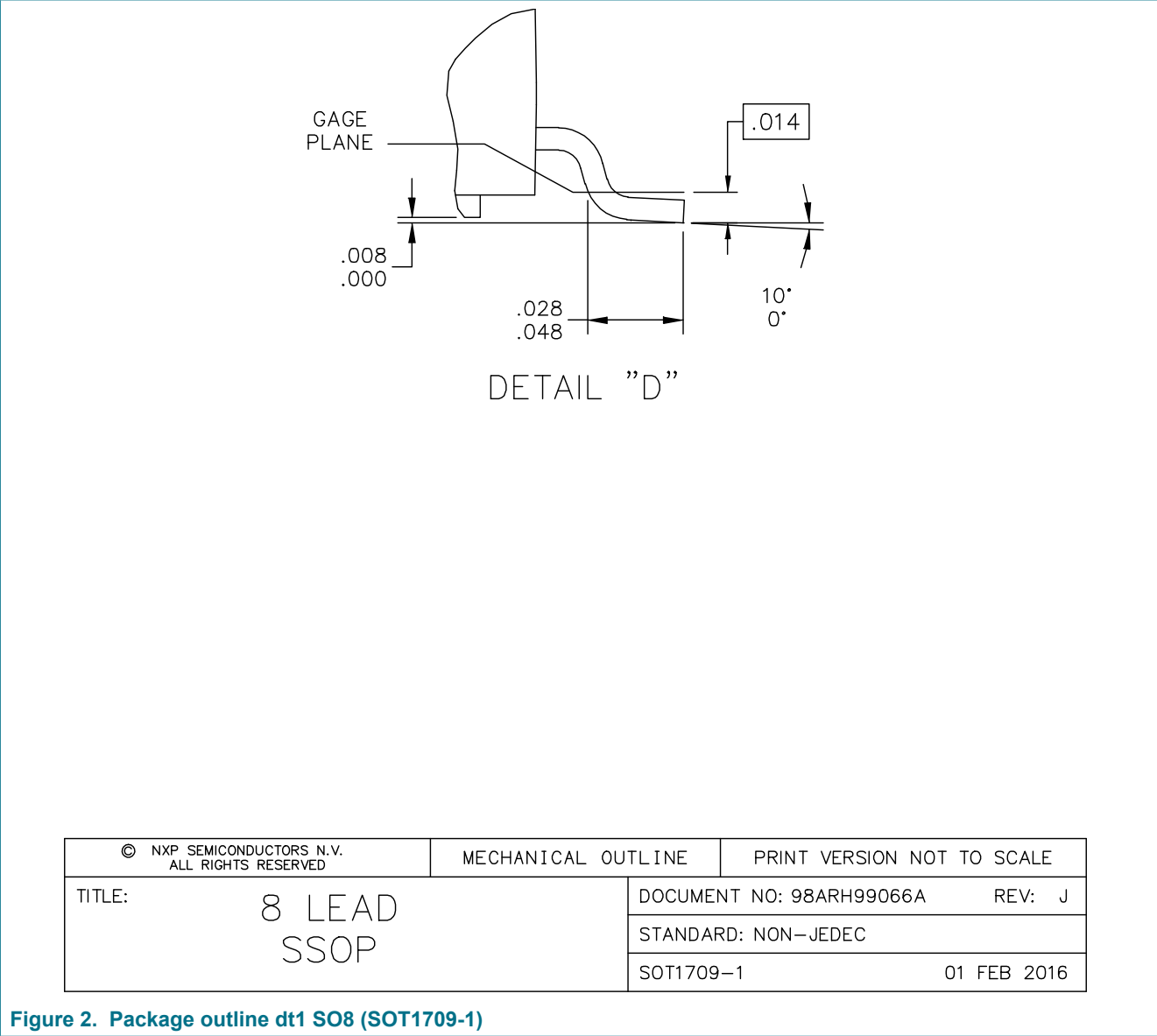


Figure 2. Package outline dt1 SO8 (SOT1709-1)

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NOTES:

- 1. ALL DIMENSIONS IN INCHES.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
- 3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.  
MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006 INCHES PER SIDE.
- 4. ALL VERTICAL SURFACES TO BE 5° MAXIMUM.
- 5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.  
ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 INCHES MAXIMUM.

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TITLE: 8 LEAD SSOP	DOCUMENT NO: 98ARH99066A      REV: J	
	STANDARD: NON–JEDEC	
	SOT1709–1	01 FEB 2016

Figure 3. Package outline note SO8 (SOT1709-1)

### 3 Legal information

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